

In the Claims:

Please amend the claims as follows:

1-22 (cancelled)

23. (currently amended) A sensor arrangement remotely readable by radio frequencies for determining desired quantities from sources, the arrangement comprising:

an a LC resonator which comprises a capacitor and a coil, and

a sensor element coupled to the LC resonator, whose properties change as a function of a measurable quantity, the sensor element being coupled capacitively or inductively with the LC resonator without forming a direct galvanic contact,

wherein the capacitor or the coil is configured to generate an electric field or magnetic field on a location of the sensor, and wherein the sensor element directly affects the electric field or the magnetic field generated by the capacitor or the coil.

24. (previously presented) The sensor arrangement according to claim 23, wherein the sensor element is cumulatively variable.

25. (previously presented) The sensor arrangement according to claim 23, wherein the sensor arrangement is suitable for use in monitoring deterioration of foodstuffs and medicinal substances.

26. (cancelled)

27. (currently amended) The sensor arrangement according to claim ~~26~~ 23, wherein the sensor element capacitively couples to the LC resonator, and wherein the ~~capacitively couplable~~ sensor element is disposed on top of the coil.

28. (currently amended) The sensor arrangement according to claim ~~26~~ 23, wherein the sensor element capacitively couples to the LC resonator, and wherein the ~~capacitively couplable~~ sensor element is disposed alone inside the package.

29. (cancelled)

30. (currently amended) The sensor arrangement according to claim ~~29~~ 23, wherein the sensor element inductively couples to the LC resonator, and wherein the ~~inductively couplable~~ sensor element is disposed in the middle of the coil.

31. (currently amended) The sensor arrangement according to claim ~~29~~ 23, wherein the sensor element inductively couples to the LC resonator, and wherein the ~~inductively couplable~~ sensor element is disposed alone inside the package.

32. (previously presented) The sensor arrangement according to claim 31, wherein the inductively couplable sensor element is disposed inside an electrically conductive ring which is thicker than the sensor element.

33. (previously presented) The sensor arrangement according to claim 32, wherein the ring is circular, oval or polygonal in shape.

34-43 (cancelled)